1CLR

1J [] 2 1K [] 3

1CLK [

1PRE 5

10 **[**7

GND 8

1Q 6

4

CD54AC109 ... F PACKAGE CD74AC109 ... E OR M PACKAGE

(TOP VIEW)

16 VCC

14 2J

13 2K

10 2Q

9 2 Q

15 2 2 CLR

12 2CLK

11 2PRE

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
  Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

# description/ordering information

The 'AC109 devices contain two independent J- $\overline{K}$  positive-edge-triggered flip-flops. A low level at the preset (PRE) or clear ( $\overline{CLR}$ ) inputs sets or resets the outputs, regardless of the levels of the other inputs. When  $\overline{PRE}$  and  $\overline{CLR}$  are inactive (high), data at the J and  $\overline{K}$  inputs meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the J and  $\overline{K}$  inputs can be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding  $\overline{K}$  and tying J high. They also can perform as D-type flip-flops if J and  $\overline{K}$  are tied together.

T <sub>A</sub>	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC109E	CD74AC109E
–55°C to 125°C	SOIC – M	Tape and reel	CD74AC109M96	AC109M
	CDIP – F	Tube	CD54AC109F3A	CD54AC109F3A

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

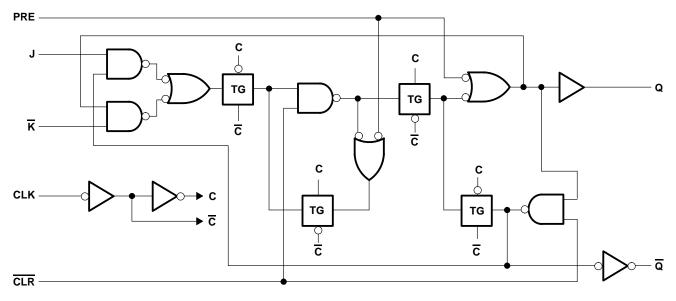


Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

			TION T			
		INPUTS			OUTI	PUTS
PRE	CLR	CLK	J	ĸ	Q	Ø
L	Н	Х	Х	Х	Н	L
Н	L	Х	Х	Х	L	н
L	L	х	Х	Х	н†	H‡
н	Н	$\uparrow$	L	L	L	н
Н	Н	$\uparrow$	Н	L	Тор	gle
н	н	$\uparrow$	L	Н	Q0	Q0
Н	Н	$\uparrow$	Н	Н	н	L
Н	Н	L	Х	Х	Q0	Q0

<sup>†</sup> Unpredictable and unstable condition if both PRE and CLR go low simultaneously

## logic diagram, each flip-flop (positive logic)





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ V or $V_I > V_{CC}$ ) (see Note 1)	
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 V or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, I <sub>O</sub> (V <sub>O</sub> > 0 V or V <sub>O</sub> < V <sub>CC</sub> )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

			T <sub>A</sub> = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		V
VIH	High-level input voltage	$V_{CC} = 3 V$	2.1		2.1		2.1		
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
	Low-level input voltage	V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	
VIL		$V_{CC} = 3 V$		0.9		0.9		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA
IOL	Low-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		24		24		24	mA
A+/A.v	Input transition rise or fell rate	$V_{CC}$ = 1.5 V to 3 V		50		50		50	ns/V
$\Delta t / \Delta v$	Input transition rise or fall rate	$V_{CC}$ = 3.6 V to 5.5 V		20		20		20	115/ V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	PARAMETER TEST CONDITIO		Vcc		25°C	–55°C to 125°C		–40°C to 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			1.5 V	1.4		1.4		1.4		
		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
VOH	VI = VIH or VIL	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{+}$	5.5 V			3.85				
		$I_{OH} = -75 \text{ mA}^{+}$	5.5 V					3.85		
			1.5 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL	VI = VIH or VIL	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65			
		I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V						1.65	
lj	$V_I = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		80		40	μA
Ci					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

#### timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 1.5 V (unless otherwise noted)

				–55°C to 125°C		–40°C to 85°C	
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			8		9	MHz
+	Pulse duration	CLK high or low	63		55		ns
tw		CLR or PRE low	56		49		115
t <sub>su</sub>	Setup time, before CLK1	J or K	69		61		ns
t <sub>h</sub>	Hold time, after CLK↑	J or K	0		0		ns
trec	Recovery time, before CLK <sup>↑</sup>	CLR↑ or PRE↑	31		27		ns



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### timing requirements over recommended operating free-air temperature range, V\_{CC} = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

				–55°C to 125°C		–40°C to 85°C	
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			71		81	MHz
	Dulas duration	CLK high or low	7		6		-
١W	t <sub>w</sub> Pulse duration	CLR or PRE	6.3		5.5		ns
t <sub>su</sub>	Setup time, before CLK <sup>↑</sup>	J or K	7.7		6.8		ns
t <sub>h</sub>	Hold time, after CLK↑	J or K	0		0		ns
trec	Recovery time, before CLK↑	CLR↑ or PRE↑	3.5		3.1		ns

#### timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V $\pm$ 0.5 V (unless otherwise noted)

			–55° 125		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
fclock	Clock frequency			100		114	MHz
	Dulas duration	CLK high or low	5		4.4		
١W	w Pulse duration	CLR or PRE	4.5		3.9		ns
t <sub>su</sub>	Setup time, before CLK <sup>↑</sup>	J or K	5.5		4.8		ns
t <sub>h</sub>	Hold time, after CLK1	J or K	0		0		ns
t <sub>rec</sub>	Recovery time, before CLK <sup>↑</sup>	CLR↑ or PRE↑	2.5		2.2		ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 1.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
		(6611 61)	MIN	MAX	MIN	MAX	
fmax			8		9		MHz
t=	CLK			129		117	-
<sup>t</sup> PLH	CLR or PRE			153		139	ns
to, u	CLK	0 ar 2		129		117	-
<sup>t</sup> PHL	CLR or PRE	Q or Q		153		139	ns

#### switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V ± 0.3 V, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
		(6611 61)	MIN	MAX	MIN	MAX	
fmax			71		81		MHz
tour	CLK	Q or $\overline{Q}$	3.6	14.4	3.7	13.1	
<sup>t</sup> PLH	CLR or PRE		4.3	17.1	4.4	15.5	ns
to u	CLK	Q or Q	3.6	14.4	3.7	13.1	
<sup>t</sup> PHL	CLR or PRE		4.3	17.1	4.4	15.5	ns



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

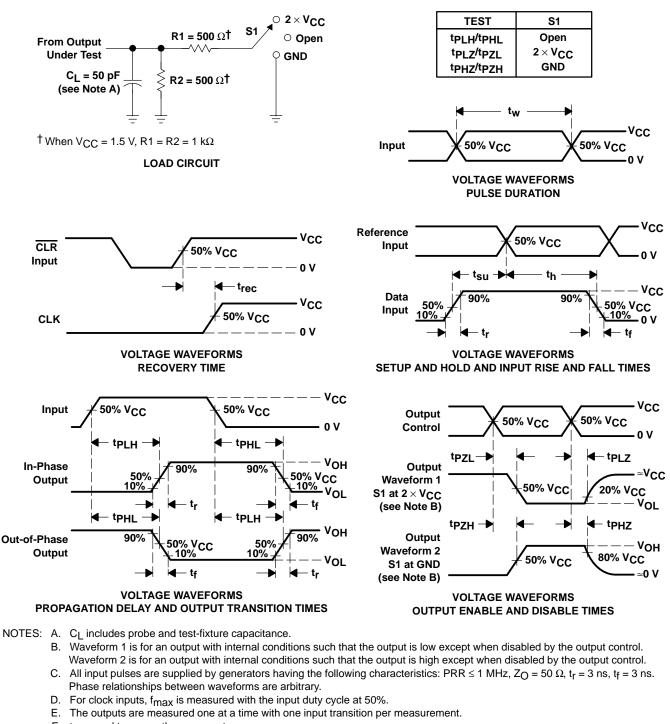
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
		(6611 61)	MIN	MAX	MIN	MAX	
fmax			100		114		MHz
<b>t</b> =	CLK	Q or $\overline{Q}$	2.6	10.3	2.7	9.4	
<sup>t</sup> PLH	CLR or PRE		3.1	12.2	3.2	11.1	ns
to	CLK	Q or Q	2.6	10.3	2.7	9.4	ns
<sup>t</sup> PHL	CLR or PRE		3.1	12.2	3.2	11.1	

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

	PARAMETER	TYP	UNIT
Cpd	Power dissipation capacitance	56	pF



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PARAMETER MEASUREMENT INFORMATION

- F. tpLH and tpHL are the same as  $t_{pd}$ .
- G. tpzL and tpzH are the same as ten.
- H. tPLZ and tPHZ are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
CD54AC109F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54AC109F3A	Samples
CD74AC109E	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC109E	Samples
CD74AC109M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC109M	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE OPTION ADDENDUM

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF CD54AC109, CD74AC109 :

- Catalog : CD74AC109
- Military : CD54AC109

NOTE: Qualified Version Definitions:

#### Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

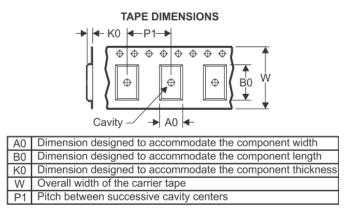
# PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
-----------------------------	--

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC109M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

5-Jan-2022



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC109M96	SOIC	D	16	2500	340.5	336.1	32.0



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5-Jan-2022

## TUBE



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74AC109E	N	PDIP	16	25	506	13.97	11230	4.32
CD74AC109E	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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